

# EUROPEAN PATENT OFFICE

## Patent Abstracts of Japan

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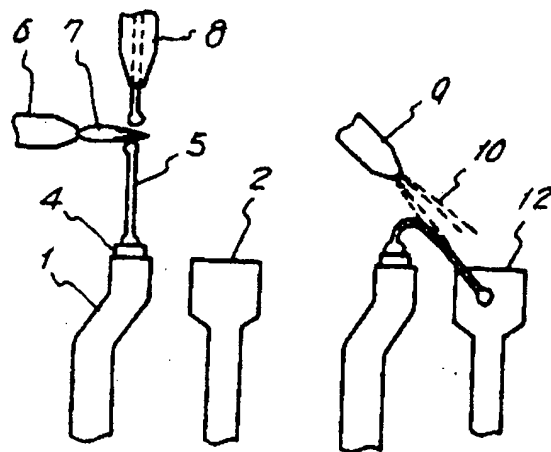
APPLICATION DATE : 13-11-80  
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APPLICANT : NEC CORP;

INVENTOR : NUMATA AKINORI;

INT.CL. : H01L 21/603 B23K 1/12

TITLE : BONDING OF FINE METAL WIRE



ABSTRACT : PURPOSE: To perform bonding of another end of wire to another side lead frame easily and accurately when a lead frame is made to stand vertically and wire bonding is to be performed between a semiconductor element mounted on the tip end of the lead and the other side lead.

CONSTITUTION: One end of the metal 5 is bonded by a capillary 8 to the semiconductor element 4 mounted on the tip end of the lead wire 1 for mounting of semiconductor element, and is melted to be cut off at the prescribed length by hydrogen torch flame 7. The other end of the gold wire 5 is blown down toward the side of the lead 12 to be bonded by high pressure air 10 blowing from an air nozzle 9, and is bonded to the side of tip end of the lead 12 with a wedge. Accordingly bonding can be performed efficiently without generating disconnection of bonding in spite of unevenness of blowing down of the gold wire 5.

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